



### Le9502 Ringing Subscriber Line Interface Circuit VE950 Series

### **APPLICATIONS**

- Short/Medium Loop: approximately 2000 ft. of 26 AWG, and 5 REN loads
- Voice over IP/DSL Integrated Access Devices, Smart Residential Gateways, Home Gateway/Router
- Cable Telephony NIU, Set-Top Box, Home Side Box, Cable Modem, Cable PC
- Fiber-Fiber In The Loop (FITL), Fiber to the Home (FTTH)
- Wireless Local Loop, Intelligent PBX, ISDN NT1/TA

### **FEATURES**

- Integrated Dual-Channel Device
  - Built-in boost switching power supply tracks line voltage minimizing power dissipation
  - Only +3.3 V and +12 V (nominal) required
  - Wide range of input voltages (+8 V to +40 V) supported
  - Minimal external discrete components
  - 44-pin eTQFP package
- Ringing
  - 70 Vpk into 5REN
  - 90 Vpk capable
  - Sinusoidal or trapezoidal capability
  - DC offset support
  - Common differential interface for both channels
- World Wide programmability:
  - Two-wire AC impedance
  - Dual Current Limit
  - Loop closure and ring trip thresholds
- Five SLIC States, including:
  - Low power Standby state
  - Reverse Polarity

### **RELATED LITERATURE**

- 081189 Le9500 RSLIC Device Data Sheet
- 081208 Le9501 RSLIC Device Data Sheet
- 080696 Le77D11 VoSLIC<sup>™</sup> Device Data Sheet
- 080697 Le78D11 VoSLAC<sup>™</sup> Device Sheet
- 080716 Le77D11 /Le78D11 Chip Set User's Guide
- 080780 Layout Considerations for the Le77D11 and Le9502 Devices Application Note

### **ORDERING INFORMATION**

Device	Package <sup>1</sup>	Packing <sup>2</sup>
Le9502BTC	44-pin eTQFP (Green Package)	Tray

- 1. The green package meets RoHS Directive 2002/95/EC of the European Council to minimize the environmental impact of electrical equipment.
- 2. For delivery using a tape and reel packing system, add a "T" suffix to the OPN (Ordering Part Number) when placing an order.

### DESCRIPTION

The Zarlink Le9502 Ringing Subscriber Line Interface Circuit (RSLIC) device from the VE950 series has enhanced and optimized features to directly address the requirements of Voice over Broadband applications. Its goal is to reduce system level costs, space, and power through higher levels of integration, and to reduce the total cost of ownership by offering better quality of service. The Le9502 RSLIC device provides a totally configurable solution to the BORSCHT functions for two lines. The resulting system is less complex, smaller, and denser, yet cost effective with minimal external components.

The Le9502 RSLIC device requires only two power supplies: +3.3 VDC and nominally +12 VDC. The latter power supply can range from +8 VDC to +40 VDC, depending on the application. A single TTL-level clock source drives an external transistor which controls the ramp voltage that in turn feeds the switching regulators. Five programmable states are available: Active, Reverse Polarity, Ringing, Standby, and Disconnect. The DC feed, two-wire AC input impedance, hook-switch threshold, and ring trip threshold are programmable via external discrete components. Binary fault detection is provided upon application of fault conditions or thermal overload.

### **BLOCK DIAGRAM**



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### PRODUCT DESCRIPTION

The VE950 series Le9502 RSLIC device uses reliable, dielectrically isolated, fully complementary bipolar technology to implement BORSCHT functions for short loop applications. Internal power dissipation is minimized by two independent line voltage tracking, buck-boost switching regulators. Two power supplies are required: 3.3 V and a positive supply ( $V_{SW}$ ). A TTL-level clock is required to drive the switching regulator. Five programmable states control loop signaling, transmission, and ringing. The Le9502 RSLIC device DC current feed limit ( $I_{SC}$ ) is resistor-programmable up to 45 mA.





### **BLOCK DESCRIPTIONS**





### **Two-Wire Interface**

The two-wire interface block provides DC current and sends/receives voice signals to a telephone connected via the  $A_i$ (Tip) and  $B_i$ (Ring) pins. The  $A_i$ (Tip) and  $B_i$ (Ring) pins are also used to send the ringing signal to the telephone. The Le9502 RSLIC device can also be programmed in Disconnect state to place the  $A_i$  and  $B_i$  pins at high impedance with the Switching Regulator disabled.

### DC Feed

DC feed is controlled in the Le9502 RSLIC device. Only the current limit threshold ( $I_{LTH}$ ) can be set via the RDC pin. The current limit threshold can be set from 0 to 30 mA.

Referring to Figure 3, the DC feed curve consists of two distinct regions. The first region is a flat anti-sat region that supplies a constant Tip-Ring voltage ( $V_{AB}$  open). The second region is a constant current region that begins when the loop current reaches the programmed current limit threshold ( $I_{LTH}$ ). This region looks like a constant current source with 3.2 k $\Omega$  shunt resistor. The short circuit current is nominally 17.0 mA greater than  $I_{LTH}$ .

A block diagram of the DC feed control circuit is shown in Figure 4. In the anti-sat region, current source CS1 creates a constant reference current, which is limited to sub-voice frequencies by  $C_{LPFi}$ . This filtered current is then steered by the Polarity Control, depending on whether the SLIC mode is Standby, Normal Active, or Reverse Polarity. The steered current then takes one of two paths to the Level Shift block, where it is used to set  $V_A$  (TIP) and  $V_B$  (RING). This voltage from the Level Shift block is buffered by the output amplifiers and appears at  $A_i$  (TIP) and  $B_i$  (RING).

When  $I_{LOOP}$ /500 becomes greater than  $I_{LTH}$ /500, the difference is subtracted from CS1, and again filtered by  $C_{LPFi}$ . This reduced current causes a reduced DC feed voltage. In Standby and Normal Active,  $A_i$  (TIP) is held constant, while  $B_i$  (RING) is changed to reduce the feed voltage. In Reverse Polarity,  $A_i$  (TIP) and  $B_i$  (RING) are swapped. When  $(I_{LOOP}-I_{LTH})/500 = CS1$ , all of the current from CS1 is subtracted, making the TIP-RING voltage = 0 V. This is the short circuit condition. At least 100  $\Omega$  loop and fuse resistance are required to ensure stability of the  $A_i$  (TIP) and  $B_i$  (RING) output amplifiers.

The capacitor  $C_{LPFi}$ , in conjunction with an internal 25 k $\Omega$  resistor (not shown), is used to create a low pass filter for the DC feed loop. This capacitor should nominally be 4.7  $\mu$ F, setting a 1.4 Hz pole. The purpose of this capacitor is to stabilize the DC feed and filter any AC components.





Note:

- 1.  $R_{DC}$  = external resistor from RDC to AGND
- 2.  $V_{AB} = V_{Ai} V_{Bi}$  Tip-Ring differential voltage
- 3.  $K_{DC}$  = Le9502 RSLIC device DC current gain, which is:  $K_{DC} = \frac{1}{500}$
- 4. I<sub>SC</sub> = Loop short circuit current limit.
- 5.  $I_{LTH}$  = Loop current limit threshold.



Note:

\* denotes external components.

### Ringing

The Le9502 RSLIC device only provides a method for creating internal ringing. Internal ringing is accomplished by applying a single or differential ringing waveform using the VRINGP and VRINGM pins, and placing the Le9502 RSLIC device into the ringing state via the device's control bits. When the Le9502 RSLIC device is in the Ringing state, the gain from the Le9502 RSLIC device's differential ringing input pin to the output, is K<sub>R</sub> (the ringing voltage gain). The output waveform is a quasi-balanced waveform as shown below in Figure 5). On the positive half cycle of the input waveform, the A<sub>i</sub> (TIP) lead of the Le9502 RSLIC device is near -4 V, and the B<sub>i</sub> (RING) lead is brought negative. Likewise, on the negative half cycle of the input waveform, the B<sub>i</sub> (RING) lead of the Le9502 RSLIC device is held near -4 V, while the A<sub>i</sub> (TIP) lead is brought more negative. The low cost regulator solution, shown in the application circuit on page 20, incorporates the use of a higher power PNP bipolar switching transistor in the switching circuit that enables the Le9502 to provide a 90 Vpk ringing signal into a lower REN load. The waveform can be either sinusoidal or trapezoidal under the control of the codec device.







For the reference schematic, Zetex part FZT955 in a SOT-223 package is used. Its  $V_{CEO}$  rating is 140 V. The switching efficiency and overhead voltage of the regulator allows a robust 70 Vpk ringing signal into a 5 REN load with  $V_{SW}$  = 12 V.

### **Switcher Controller**

The switcher controller's main function is to provide a negative power supply ( $V_{REG}$ ) that tracks Tip and Ring voltage for the 2wire interface. As the Tip and Ring voltage decreases, the switcher will likewise lower  $V_{REG}$  In doing so, the switcher saves power because the device is not forced to maintain static supply voltage in all states.

The switching power supply controller uses a discontinuous mode, buck-boost voltage converter topology. The frequency of operation is set by the ISET resistor and the VRAMP capacitor values. An external clock with approximately a 10% duty cycle drives the gate (base) of a small-signal FET which is used to reset the VRAMP capacitor voltage, creating the ramp voltage used internally by the switching power supply control circuitry. This clock signal controls the switching supply's operating frequency. The switcher circuit is nominally designed for 85 kHz operation based on the <u>Application Circuit on page 20</u>.

The duty cycle of the switching transistors is continuously variable up to 90% depending on the magnitude of the error voltage on the compensation (CHS) pin. The error signal on CHS is compared to the ramp signal. The ramp rate of the VRAMP signal is set by the ISET resistor ( $R_{SET}$ ) and the VRAMP capacitor ( $C_{RAMP}$ ). A 1%  $R_{SET}$  resistor should be chosen first (see <u>Signal</u> <u>Conditioning on page 9</u>) before using the following equation to calculate  $C_{RAMP}$ 

 $C_{RAMP\_max} = I_{RAMP\_min} \bullet [(100\% - t_{CHCLK\_max}) / (f_{CHCLK} \bullet R_{SET\_max})]$ 

where  $I_{RAMP\_min}$  is the current going through  $C_{RAMP}$ ,  $t_{CHCLK\_max}$  is maximum duration of Chopper Clock High Duty Cycle provided in the specification section,  $f_{CHCLK}$  is the frequency of the chopper clock, and  $R_{SET\_max}$  is  $R_{SET\_nom} * 1.01$ . The calculated value for  $C_{RAMP}$  is the maximum value that can guarantee the switcher to operate. A NPO dielectric capacitor is recommended for  $C_{RAMP}$ .

When the external clock signal goes from a logic Low to a logic High, it will pull VRAMP voltage low which causes internal clock (from the square wave converter) to go Low, turning on the external power switch. When the external clock signal goes from High to Low, C<sub>RAMP</sub> will charge up. When the VRAMP voltage exceeds internal voltage threshold, the rising edge of the internal clock from the square wave converter will reset the current limit latch getting it ready for the next cycle and turn off the external power switch. Also on a cycle-by-cycle basis, one of the following three events will shut off the power switch, depending on which event occurs first:

- a) The VRAMP voltage exceeds the error voltage that is integrated on the CHS node (normal voltage feedback operation.)
- b) The VRAMP voltage exceeds the internal voltage threshold.
- c) The power switch current limit threshold is reached (set by R<sub>LIM</sub>).

Cycle-by-cycle current limiting is provided by the current sense  $ILS_i$  pin which senses the external power switch current through the resistor  $R_{LIM}$ . If this pin exceeds  $VT_{ILS}$ , nominally –0.28 V with respect to  $V_{SW}$ , the switching supply will set the current limit latch and shut off the external switch drive until the next time the VRAMP pin is pulled Low to reset the latch. Thus the peak inductor current, and also peak switching converter power output can be controlled on a cycle-by-cycle basis and set by the equation  $I_{LIM} = (VT_{ILS})/R_{LIM}$ .

This sensing configuration has the added benefit that if the clock signal is removed for some reason, the power switch cannot be left on indefinitely. Leaving the  $ILS_i$  pin unconnected or shorting this pin to VSW will disable current limiting, but is not recommended.

A leading edge blanking filter is added at the output of the latch to ignore the first 150 ns of a current limit event. This feature is used to ignore a false current trip that may be caused by the power switch driving the reverse recovery charge ( $Q_{RR}$ ) of the external power rectifier.

The on chip driver is designed to drive either an external PNP or a PMOS power device. Its output drive is clamped between 7-9 V below  $V_{SW}$ , and can source or sink approximately 100 mA. The driver has approximately 50  $\Omega$  of source resistance. The additional resistance should be added from the SD<sub>i</sub> pin to the base of the external power device if a PNP is used to limit base drive for optimal efficiency.

When using a PMOS power switch, the SD<sub>i</sub> pin will be able to drive approximately 100 mA of drive current to the gate of the PMOS device, and an internal clamp will limit the drive between 7-9 V. To keep system losses to a minimum, it is recommended that low gate charge be given higher consideration over low  $r_{DS(on)}$  when selecting a power PMOS device for your application.

Figure 6. Switching Power Supply Block Diagram



Note:

\* Denotes external components.

\*\* Generated internally by band gap  $\cong$  1.4 V.

\*\*\*  $V_{RING} = V_{RINGP} - V_{RINGM}$ 

\*\*\*\* Preferably, the external clock should be Low in startup. For a system (codec) which has a high impedance at the clock output in start up, the additional  $R_{Base}$  and  $R_{BG}$  resistors are recommended with values of 10 k $\Omega$  and 100 k $\Omega$  respectively.

### Signal Transmission

In Normal Active and Reverse Polarity states, the AC line current is sensed across the  $R_S$  resistors (see Figure 7), summed and attenuated, and converted to voltage at the CFILT<sub>i</sub> pin. The voltage then goes through a high pass filter implemented using the external  $C_{HPi}$  capacitor, is amplified, and sent to the codec device at the VOUT<sub>i</sub> pin. This output is proportional to the AC metallic component of the line voltage. Additionally, the signal transmission block receives the analog signal from the codec device. The analog signal is amplified and sent to the line. Finally, a proportion of the signal at  $V_{OUT}$  is fed back to the line.

There are three parameters which define the AC characteristics of the Le9502 RSLIC device. First is the input impedance presented to the line or 2-wire ( $V_{AB}$ ) side ( $Z_{2WIN}$ ), second is the gain from the 4-wire ( $V_{IN}$ ) to the 2-wire ( $V_{AB}$ ) side ( $G_{42}$ ), and third is the gain from the 2-wire ( $V_{AB}$ ) side to the 4-wire ( $V_{OUT}$ ) side ( $G_{24}$ ).

### Input Impedance (Z<sub>2WIN</sub>)

 $Z_{2WIN}$  is the impedance presented to the line at the 2-wire side and is defined by:

$$Z_{2WIN} = 2R_F + K_V K_{OUT} R_{IMT}$$

where  $2 \cdot R_F$  is the total resistance of the external fuse resistors in the circuit,  $R_{IMT}$  is the impedance setting resistor for return loss purpose,  $K_{OUT}$  is the gain from  $V_{OUT}$  to  $V_{AB}$ , and  $K_V$  is the voice current gain defined in the Transmission Specifications Table. Note that the equation reveals that  $Z_{2WIN}$  is a function of the selectable resistors,  $R_{IMT}$  and  $R_F$ . For example, if  $R_F = 0 \Omega$ and  $R_{IMT}$  is 100 k, the terminating impedance is 600  $\Omega$ . This is the configuration used in this data sheet for defining the device specifications. However, in a real application,  $R_F = 50 \Omega$  is recommended, and RIMT is set to 80.6 K $\Omega$  to provide an approximate 600  $\Omega$  input impedance.

### 2-Wire to 4-Wire Gain (G<sub>24</sub>)

The 2-wire to 4-wire gain is the gain from the phone line to the VOUT output of the Le9502 RSLIC device. To solve for  $G_{24}$ , set  $V_{IN} = V_{INP} - V_{INM} = 0 V$  (see Figure 7).

$$\frac{V_{OUT}}{V_{AB}} = G_{24} = \frac{1}{\frac{2R_F}{K_V R_{IMT}} + K_{OUT}}$$

or

$$\label{eq:G24} G_{24} \,=\, -20 \text{log} \Big( K_{\text{OUT}} + \frac{2 R_{\text{F}}}{K_{\text{V}} R_{\text{IMT}}} \Big) \quad \text{in dB}$$

### 4-Wire to 2-Wire Gain (G<sub>42</sub>)

 $G_{42}$  is the gain from the VIN input to the line. This gain is defined as  $V_{AB}/V_{IN}$ . For the analysis of  $G_{42}$ , substitute the load resistor  $R_L$  in place of the test voltage source  $V_T$  (see Figure 7).

$$\frac{V_{AB}}{V_{IN}} = G_{42} = \frac{K_{IN} \left(\frac{R_L}{R_L + 2R_F}\right)}{\left(1 + \frac{K_{OUT}R_{IMT}K_V}{R_I + 2R_F}\right)}$$

or

$$G_{42} = -20 \log \left( \frac{\kappa_{IN} \left( \frac{R_L}{R_L + 2R_F} \right)}{\left( 1 + \frac{\kappa_{OUT} R_{IMT} \kappa_V}{R_L + 2R_F} \right)} \right) \text{ in dB}$$

where  $K_{IN}$  is the gain from VIN to  $V_{AB}$ .





Note:

\* denotes external components.

### **Fault Detection**

Each channel of the Le9502 RSLIC device has a fault detection pin,  $\overline{F}_1$  or  $\overline{F}_2$ . These pins are driven low when a longitudinal current fault or foreign voltage fault occurs. When not in Disconnect state, there are three conditions that will cause the  $\overline{F}_i$  pin to indicate a fault condition:

- $|I_A I_B| > I_{LONG}$
- In Normal Active and Standby state, a foreign voltage fault occurs in which V<sub>A</sub> is above ground or V<sub>B</sub> is close to V<sub>REG</sub>.
- In Reverse Polarity state, a foreign voltage fault occurs in which V<sub>B</sub> is above ground or V<sub>A</sub> is close to V<sub>REG</sub>.

In the Disconnect state, fault detection is not supported.

### **Signal Conditioning**

The  $\overline{\text{DET}}_i$  outputs are used for both off-hook and ring trip detection. The threshold for each of these functions is set by external components.

If the Le9502 RSLIC device is in Low Power Standby or Normal Active modes, the  $\overline{\text{DET}}_i$  output is used to indicate an off-hook condition. The following equation will set the off-hook threshold:

$$R_{SET} = \frac{500 \bullet V_{REF}}{I_{offhook\_threshold}}$$

where  $I_{offhook\_threshold}$  is a user-chosen off-hook current threshold.  $R_{SET}$  is 68.1 k $\Omega$  as specified in the <u>Application Circuit on</u> page 20. This value produces a nominal off-hook threshold of 10.3 mA.

If the SLIC device is in the Ringing state, the  $\overline{\text{DET}}_i$  output will indicate the ring trip condition. The threshold for ring trip detection is set with an external resistor,  $R_{\text{TRIP}}$ , from the RTRIP<sub>i</sub> to VREG<sub>i</sub> pins. The ring trip threshold is set on a per-channel basis. To select the value of  $R_{\text{TRIP}}$ , the following equation is used:

$$R_{TRIP} = \frac{500 \bullet (V_{RING PK} + 10 V)}{I_{trip threshold}}$$

where

$$V_{RING PK} + 10 V(overhead voltage) \approx V_{REG}$$
,

For Zarlink's application, the ring trip current threshold is 74.6 mA which results in a R  $_{TRIP}$  value of 536 k $\Omega$ . C<sub>TRIP</sub> is used as a transient filter to debounce the output ring trip signal at the  $\overline{\text{DET}}_i$  pin. The value for C<sub>TRIP</sub> is nominally 47 nF as in the <u>Application</u> <u>Circuit on page 20</u>.

The RDC<sub>i</sub> pin is used to set the DC feed current limit, as described in <u>DC Feed on page 4</u>.

### **Thermal Overload**

When the die temperature around the power amplifier of a Le9502 RSLIC device channel reaches approximately 160° C, the  $\overline{F_i}$  pins are pulled Low and V<sub>REG</sub> will collapse. At the same time, all the blocks controlling that channel of the device are shut off, except for the logic interface block. The SLIC channel goes into a state similar to Disconnect, making the line current zero. When the temperature drops below 145° C, the SLIC channel returns to its previous state. It is important to recognize that even while a channel experiences thermal overload, the state of the device can be modified.

### **Reference Current Generator**

To set the hook switch threshold for both channels, an external resistor (R<sub>SET</sub>) from ISET to AGND pins is used. For R<sub>SET</sub> value, please refer to Line Card Parts List on page 21.

Moreover, internally this block generates I<sub>RAMP</sub> which is used to help set the frequency of operation desired for the switcher.

### **Control Logic**

Each channel of the Le9502 RSLIC device has three input pins from a codec device (CHS, C2, and C1). The inputs set the operational state of each channel. There are five operational SLIC device states (See Table 1): Low Power Standby, Disconnect, Normal Active, Reverse Polarity, and Ringing

CHS	C2	C1	Operating State	Description
Float	0	0	Low Power Standby	Voice Transmission Disabled. Loop current capability is reduced.
Float	0	1	Reverse Polarity	Similar to normal active, but DC polarity is reversed so that the Ring lead is more positive than the Tip. Supports on hook transmission.
Float	1	0	Normal Active	SLIC device fully operational. Supports on hook transmission.
Float	1	1	Ringing	Ringing state with $V_{AB}$ set to $K_R \cdot (V_{RINGP} - V_{RINGM})$ . The switching supply maintains minimum headroom for the sourcing and sinking amplifiers in order to maximize power efficiency.
Pull Low *	0	0	Disconnect**	SLIC device is shut down. Mainly used if a line fault is detected or to shut down a line.

### Table 1. SLIC Device Operating States

Note:

\* See CHS Specifications on page 17.

\*\* Standby state with switcher turned off.

### **CONNECTION DIAGRAM**



### Note:

1. Pin 1 is marked for orientation.

### **PIN DESCRIPTIONS**

Pin Name	Туре	Description
AGND	Ground	Analog and digital ground return for VCC circuitry (common to both channels).
A <sub>1,2</sub> (TIP)	Output	A (TIP lead) power amplifier output for channels 1 and 2.
BGND <sub>1,2</sub>	Ground	Battery ground return for power amplifiers on channel 1 and 2.
B <sub>1,2</sub> (RING)	Output	B (RING lead) power amplifier output for channels 1 and 2.
C1 <sub>1</sub> , C2 <sub>1</sub>	Input	Logic control inputs to control channel 1 state.
C1 <sub>2</sub> , C2 <sub>2</sub>	Input	Logic control inputs to control channel 2 state.
CFILT <sub>1,2</sub>	Output	AC coupling pin for 4-wire amplifier
CHS <sub>1,2</sub>	Input	Compensation node for switching power supply channels 1 and 2.
DET <sub>1,2</sub>	Output	Loop detector or ring trip detector output, depending on state of control bits. If the SLIC device is in Ringing state then ring trip indication is given, if the SLIC device is in Low Power Standby, Normal Active or Reverse Polarity then hook switch indication is given.
F <sub>1,2</sub>	Output	Fault detect pin for channels 1 and 2. A low indicates a fault for the respective channel, which can be triggered by large longitudinal current, ground key, or thermal overload.
ILS <sub>1,2</sub>	Input	Voltage sense pin to limit peak current in external switching power supply transistor (channels 1 and 2).
ISET	Input	Dual purpose pin: 1. sets the hook switch detection threshold (for both channels); 2. sets the current source for triangle wave generation for the switching power supply.
LPF <sub>1,2</sub>	Output	A capacitor tied to from this pin to AGND stabilizes the DC feed loop, and lowers Idle Channel Noise.
RDC	Input	Resistor connection to GND. Sets DC feed current limit, I <sub>LTH</sub> (common to both channels).
RTRIP <sub>1,2</sub>	Input	Network tied from RTRIP to VREG. Sets the ring trip threshold detection level.
SD <sub>1,2</sub>	Output	Base (gate) drive for switching power supply transistor (channels 1 and 2).
VCC	Supply	Positive supply for internal VCC circuitry (common to both channels).
VHP <sub>1,2</sub>	Output	High pass invert summing node of the VOUT amplifier driven by the AC current coming from $CFILT_1$ and $CFILT_2$ .
VOUT <sub>1,2</sub>	Output	Analog (4-wire side) VOUT amplifier transmit output
VINM <sub>1,2</sub> VINP <sub>1,2</sub>	Input	Differential (P-M) analog (4-wire side) voice signal input.
VRAMP	Input	Switching power supply ramp voltage that sets the frequency of the switcher and the maximum duty cycle (common to both channels).
VREG <sub>1,2</sub>	Supply	Negative power supply generated by SLIC device Switching Regulator. (channels 1 and 2)
VRINGP, VRINGM	Input	Differential ringing input (common to both channels).
VSW	Supply	Positive supply used by the SLIC device to generate the negative regulated supplies of VREG <sub>1</sub> , VREG <sub>2</sub> (common to both channels).
Exposed Pad	Isolated	Exposed pad on underside of device must be connected to a heat spreading area. The AGND plane is recommended.

### **ABSOLUTE MAXIMUM RATINGS**

Storage temperature	–55 to +150°C
Ambient temperature, under bias	–40° to +85°C
V <sub>CC</sub> with respect to AGND	–0.4 to +6.5 V
V <sub>REG</sub> with respect to BGND	+0.4 to -115 V
BGND with respect to AGND	-100 to 100 mV
A (TIP) or B (RING) to BGND:	
Continuous	V <sub>REG</sub> –1 to BGND +1
10 ms (F = 0.1 Hz)	V <sub>REG</sub> –5 to BGND +5
1 μs (F = 0.1 Hz)	V <sub>REG</sub> –10 to BGND +10
250 ns (F = 0.1 Hz)	V <sub>REG</sub> –15 to BGND +15
Current from A (TIP) or B (RING)	±150 mA
C1 and C2 with respect to AGND	-0.4 to VCC + 0.4 V
CHCLK	AGND to VCC
V <sub>SW</sub>	BGND to +44 V
Maximum power dissipation, T <sub>A</sub> = 85° C (See notes)	1.8 W
Thermal Data:	θ <sub>JA</sub>
In 44-pin eTQFP package	32° C/W
Thermal Data:	θ <sub>JC</sub>
In 44-pin eTQFP package	9.2° C/W
ESD Immunity (Human Body Model)	JESD22 Class 1C compliant

Stresses above those listed under *Absolute Maximum Ratings* can cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods can affect device reliability.

Note:

Thermal limiting circuitry on chip will shut down the circuit at a junction temperature of about 160°C. Continuous operation above 145°C junction temperature may degrade device reliability.

The thermal performance of a thermally enhanced package is assured through optimized printed circuit board layout. Specified performance requires that the exposed thermal pad be soldered to an equally sized exposed copper surface, which, in turn, conducts heat through 16 0.3 mm diameter vias on a 1.27 mm pitch to a large (> 500 mm<sup>2</sup>) internal copper plane. (Refer to Zarlink application note Layout Considerations for the Le77D112 and Le9502 RSLIC devices, document ID# 081013).

### Package Assembly

Green package devices are assembled with enhanced environmental, compatible lead-free, halogen-free, and antimony-free materials. The leads possess a matte-tin plating which is compatible with conventional board assembly processes or newer lead-free board assembly processes. The peak soldering temperature should not exceed 245°C during printed circuit board assembly.

Refer to IPC/JEDEC J-Std-020B Table 5-2 for the recommended solder reflow temperature profile.

### **OPERATING RANGES**

Zarlink guarantees the performance of this device over commercial (0° to 70°C) and industrial (-40° to 85°C) temperature ranges by conducting electrical characterization over each range, and by conducting a production test with single insertion coupled to periodic sampling. These characterization and test procedures comply with section 4.6.2 of Bellcore GR-357-CORE Component Reliability Assurance Requirements for Telecommunications Equipment.

### **Environmental Ranges**

Ambient Temperature	-40° to +85° C	

### **Electrical Ranges**

V <sub>CC</sub>	3.3 V ± 5%
V <sub>SW</sub>	8 to 40 V
V <sub>REG</sub>	-7 to -110 (0 V in Disconnect state).

Le9502

## ELECTRICAL CHARACTERISTICS

Unless otherwise noted, test conditions are:  $V_{CC} = 3.3$  V,  $V_{SW} = 12.0$  V, AGND = BGND, no fuse resistors,  $R_L = 600 \Omega$ , 85 kHz CHCLK,  $I_{LTH}$ =20 mA ( $R_{DC} = 34.8 k\Omega$ ). Ringing configuration is  $V_{RING} = V_{RINGP} - V_{RINGM} = 0.7$  Vpk. 20 Hz sinusoidal. Please refer to Test Circuit on page 19 for all other component values.

# **Supply Currents and Power Dissipation**

<b>Operation States</b>	Condition	3.3 V V(	3.3 V VCC Supply Current (mA)	Current	VREG Su	VREG Supply Current (mA) (Note 4)	ent (mA)	VREG Su	VREG Supply Power (mW)	er (mW)	SLIC D	SLIC Device Power (mW) (Note 5)	er (mW)	VSW Pin Current (mA)	Note
		Min	Typ	Мах	Min	Тур	Мах	Min	Typ	Мах	Min	Тур	Мах	Typ	
Standby	R <sub>L</sub> = open V <sub>IN</sub> =0 V	3.0	5.5	8.0	0.25	1.0	3.5	15.0	50.0	130.0	20.0	75.0	130.0	2.0	-
Disconnect	R <sub>L</sub> = open V <sub>IN</sub> = 0 V	2.0	5.0	7.5	I	0.1	I	0.0	0.5	3.0	5.0	15.0	25.0	0.1	~
	R <sub>L</sub> = open V <sub>IN</sub> = 0 V	4.0	2.0	10.0	1.0	3.0	5.0	50.0	200.0	360.0	100.0	215.0	320.0	2.5	-
Active	R <sub>L</sub> = 300 Ω V <sub>IN</sub> = 0 V	4.0	7.5	10.0	28.0	38.0	48.0	500.0	850.0	1150.0	250.0	475.0	650.0	4.1	-
	R <sub>L</sub> = 900 Ω V <sub>IN</sub> = 0 V	Ι	7.0	-	I	26.0	Ι	I	820.0	I	I	360.0	Ι	4.6	1,2
	R <sub>L</sub> = open V <sub>IN</sub> = 0 V	4.0	7.0	10.0	1.0	3.0	5.0	50.0	200.0	360.0	100.0	215.0	320.0	2.5	1,2
Pol Rev	R <sub>L</sub> = 300 Ω V <sub>IN</sub> = 0 V	4.0	7.5	10.0	28.0	38.0	48.0	500.0	850.0	1150.0	250.0	525.0	650.0	4.1	-
	R <sub>L</sub> = 900 Ω V <sub>IN</sub> = 0 V	Ι	2.0		I	26.0	I	I	833.0	I	I	360.0	Ι	4.6	1,2
Rindind	R <sub>L</sub> = open V <sub>RING</sub> = 0.7 Vac	Ι	7.0		Ι	3.0	Ι	I	152.0	Ι	Ι	180.0	Ι	2.1	1,2
D D	R <sub>L</sub> = 1400 Ω V <sub>RING</sub> = 0.7 Vac	4.0	7.5	10.0	33.0	38.0	42.0	2000.0	2500.0	2900.0	500.0	800.0	1010.0	5.7	1, 3

Notes:

Values shown are for one channel only but are tested with both channels in the same state. Not tested in production. Parameter is guaranteed by characterization or correlation to other tests. Production test forces Vin=0.5Vdc which is equivalent to V<sub>RING</sub>=0.7Vac. ۲. ni m

 $I_{VSW} = \frac{V_{REG} \bullet I_{VREG}}{\sum_{n=0}^{N} V}$ , where  $\eta = efficiency$ . For our recommended circuit, an efficiency of 0.6 can be assumed under heavy loads. η•V<sub>SW</sub> 4

SLIC device power is defined as the power delivered through the VCC and VREG pins minus the power delivered to the load. It does not include any power associated with the VSW pin and the external switcher. ς.

### SPECIFICATIONS

### **Device Specifications**

Specification	Condition	Min	Тур	Max	Unit	Note
Line Characteristics						
$V_A$ , Active $V_B$ , Reverse Polarity	R <sub>L</sub> = open		-4			
V <sub>A</sub>	Standby, R <sub>L</sub> = open		–1			
V <sub>AB</sub>	Active or Reverse Polarity, R <sub>L</sub> = open	45	48	53	v	<u>1.</u>
	Standby, R <sub>L</sub> = open	45	48	54.5		
V <sub>REG</sub>	Active or Reverse Polarity, R <sub>L</sub> = open	-50	-63	-69		<u>4.</u>
	Standby, R <sub>L</sub> = open	-48	-58	-64		
Current limit threshold, I <sub>LTH</sub> accuracy	Active or Reverse Polarity and Standby	17.5	20	22.5		<u>4.</u>
1	$R_L$ = 100 Ω, Active or Reverse Polarity; I <sub>LTH</sub> =20mA.	I <sub>LTH</sub> +10	I <sub>LTH</sub> +17	I <sub>LTH</sub> +29		
I <sub>SC</sub>	$R_L$ = 100 Ω, Standby; I <sub>LTH</sub> =20mA.	I <sub>LTH</sub> +10	I <sub>LTH</sub> +17	I <sub>LTH</sub> +25	mA	
Loop Current	$R_L$ = 600 Ω, Active or Reverse Polarity; I <sub>LTH</sub> =20mA.	I <sub>LTH</sub> +7	I <sub>LTH</sub> +11	I <sub>LTH</sub> +20		
I <sub>L</sub> accuracy	R <sub>L</sub> = 600 Ω, Standby; I <sub>LTH</sub> =20mA.	I <sub>LTH</sub> +7	I <sub>LTH</sub> +11	I <sub>LTH</sub> +20		
	Output impedance		25		kΩ	
LPF <sub>i</sub>	Bias voltage with respect to GND		2.2		mA kΩ V μA Ω V mA	
	Leakage current for capacitor value of 4.7 $\mu$ F ± 20%			0.1		<u>3.</u>
RDC	Input impedance		10			
-	Input voltage tolerance	1.33	1.4	1.47	V	
Hook Switch detection threshold programming range		5		15		<u>4.</u>
Loop detect threshold tolerance (I <sub>offhook_threshold</sub> )	Standby, Active and Reverse Polarity	8.8	11.5	14.5	mA	
Ring trip current accuracy (I <sub>trip_threshold</sub> )	V <sub>REG</sub> i = -85V	59.7	80	89.5		
Ringing		1			1	1
V <sub>A</sub> , V <sub>B</sub>	$V_{RING}$ = 0 V, $R_{L}$ = 1400 $\Omega$		-4		N	<u>3.</u>
V <sub>AB</sub> offset	$V_{RING}$ = 0 V, $R_{L}$ = 1400 $\Omega$	-2		+2	v	
Ringing voltage gain (K <sub>R</sub> )	Ringing, $K_{R} = \frac{V_{AB}}{V_{RING}}$ ,	95	100	105	V/V	<u>1.</u>
	Vin = 0.7Vpk, R <sub>L</sub> = 1400Ω	0.2		2.4	V	4
VRINGP, VRINGM Input Range (VRINGP - VRINGM) Differential		-0.3		2.4	v	<u>4.</u>
Input Impedance	Pinging P = 100 O	200	405	400	kΩ	<u>3.</u>
Ringing Current Limit, I <sub>RSC</sub>	Ringing, $R_L = 100 \Omega$	90	135	180	mApk	<u>4.</u>
Ringing distortion	Vin = 0.7Vpk, R <sub>L</sub> = 1400Ω		0.5	3.5	%	
Switching Power Supply			05	00	141-	
f <sub>CHCLK</sub> Chopper Clock High Duty Cycle		80	85	90	kHz	<u>3.</u>
(t <sub>CHCLK</sub> )		7.5	10	12.5	%	<u>.</u>

put impedance ias current nutput impedance lew Rate negative lew Rate positive OH where $V_{SW} \ge 12 V$ , BD = 330 Ω OL where $V_{SW} \ge 12 V$ , BD = 330 Ω nput impedance inging tandby and Active isconnect RAMP current	0.25 -1 3 25 V <sub>SW</sub> -0.4	0.28 7000 50 V <sub>SW</sub> - 0.3 V <sub>SW</sub> - 8.0	0.31 +1 	V      Ω      μA      Ω      V/µsec	3.
ias current iutput impedance lew Rate negative lew Rate positive $OH$ where $V_{SW} \ge 12 V$ , $BD = 330 \Omega$ $OL$ where $V_{SW} \ge 12 V$ , $BD = 330 \Omega$ uput impedance inging tandby and Active isconnect	-1 3 25	7000 50 V <sub>SW</sub> - 0.3 V <sub>SW</sub> - 8.0	+1	Ω μΑ Ω	3.
ias current iutput impedance lew Rate negative lew Rate positive $OH$ where $V_{SW} \ge 12 V$ , $BD = 330 \Omega$ $OL$ where $V_{SW} \ge 12 V$ , $BD = 330 \Omega$ uput impedance inging tandby and Active isconnect	3 25	50 V <sub>SW</sub> - 0.3 V <sub>SW</sub> - 8.0		μA Ω	3.
tutput impedance lew Rate negative lew Rate positive $_{OH}$ where $V_{SW} \ge 12$ V, $_{BD}$ = 330 $\Omega$ $_{OL}$ where $V_{SW} \ge 12$ V, $_{BD}$ = 330 $\Omega$ uput impedance inging tandby and Active isconnect	3 25	V <sub>SW</sub> - 0.3 V <sub>SW</sub> - 8.0		Ω	3.
lew Rate negative lew Rate positive $_{OH}$ where $V_{SW} \ge 12 V$ , $_{BD} = 330 \Omega$ $_{OL}$ where $V_{SW} \ge 12 V$ , $_{BD} = 330 \Omega$ apput impedance inging tandby and Active isconnect	25	V <sub>SW</sub> - 0.3 V <sub>SW</sub> - 8.0	V <sub>SW</sub>		3.
lew Rate positive $_{OH}$ where $V_{SW} \ge 12 V$ , $_{BD} = 330 \Omega$ $_{OL}$ where $V_{SW} \ge 12 V$ , $_{BD} = 330 \Omega$ apput impedance inging tandby and Active isconnect	25	V <sub>SW</sub> - 8.0	V <sub>SW</sub>	- V/µsec	3.
$\begin{array}{l} & \text{OH where } V_{SW} \geq 12 \text{ V,} \\ & \text{BD} = 330 \ \Omega \\ & \text{OL where } V_{SW} \geq 12 \text{ V,} \\ & \text{BD} = 330 \ \Omega \\ & \text{aput impedance} \\ & \text{inging} \\ & \text{tandby and Active} \\ & \text{isconnect} \end{array}$		V <sub>SW</sub> - 8.0	V <sub>SW</sub>		3.
$\begin{array}{l} _{BD} = 330 \ \Omega \\ _{OL} \ \text{where} \ V_{SW} \geq 12 \ \text{V}, \\ _{BD} = 330 \ \Omega \\ _{\text{input impedance}} \\ _{\text{inging}} \\ _{\text{tandby and Active}} \\ _{\text{isconnect}} \end{array}$	V <sub>SW</sub> - 0.4	V <sub>SW</sub> - 8.0	V <sub>SW</sub>		3.
BD = 330 Ω input impedance inging tandby and Active isconnect				v	<u>ə.</u>
nput impedance inging tandby and Active isconnect				v	
inging tandby and Active isconnect					
tandby and Active		1		MΩ	
isconnect			180		-
			75	1.	
RAMP current			1	μA	
	72.0	82.2	92.9	1	
iput impedance		10		Ω	
put voltage tolerance	1.33	1.4	1.47	V	<u>3.</u>
e 2-wire Interface				<u>.I</u>	
00 to 4000 Hz, 50 mVrms	25	45		1	1
k to 50 kHz	20	40		dB	4.
00 to 4000 Hz, 100 mVrms	25	45		dB	
		40		-	<u>4.</u>
0k to 100k		-			4.
	_			<u> </u>	
= 600 Q, 300 to 3400 Hz 0				1	1
Bm, Active and Reverse olarity	46	63		dB	
kHz, 0 dBm	40	50		dB	
(TIP) or B(RING)	30			mA	<u>4.</u>
(TIP) or B(RING), to 100 Hz		1	5	Ω/pin	<u>4.</u>
low	18	26	35	mA	
	łł			+	4
00 to 3400 Hz, for 600 $\Omega$	26				<u>4.</u>
L = open, 0dBm, 2-wire	9.34	9.54	9.74	1	
	9.34	9.54	9.74		<u>4.</u>
dBm, 1 kHz	-9.74	-9.54	-9.34	- ar	
dBm, 1 kHz	3.32	3.52	3.72	1	
dBm, 1 kHz				1	
ine Test:, Standby, <  20 mA	<u>1</u> 520	$\frac{1}{500}$	$\frac{1}{480}$	A/A	<u>3.</u>
	to 50 kHz k to 100k = 600 Ω, 300 to 3400 Hz, 0 Bm, Active and Reverse blarity kHz, 0 dBm TIP) or B(RING) TIP) or B(RING), to 100 Hz low 0 to 3400 Hz, for 600 Ω = open, 0dBm, 2-wire IBm, 1 kHz IBm, 1 kHz IBm, 1 kHz IBm, 1 kHz he Test:, Standby,	to 50 kHz  20    k to 100k  15    = 600 $\Omega$ , 300 to 3400 Hz, 0  15    Bm, Active and Reverse olarity  46    blarity  40    TIP) or B(RING)  30    TIP) or B(RING), to 100 Hz  18    10 to 3400 Hz, for 600 $\Omega$ 26	$to 50 \text{ kHz}$ 20  40 $tk to 100k$ 15  30 $tk to 100k$ 46  63 $tk tz, 0 dBm$ 40  50    TIP) or B(RING)  30  1 $to 100 Hz$ 18  26 $to 100 Hz$ 18  26 $to 100 Hz$ 9.34  9.54 $to 3400 Hz, for 600 \Omega$ 26  26 $to 3400 Hz, for 600 \Omega$ 26  26 $to 10 ta 3400 Hz, for 600 \Omega$ 26  26 $to 10 ta 3400 Hz, for 600 \Omega$ 26  26 $to 10 ta 3400 Hz, for 600 \Omega$ 26  26 $to 10 ta 3400 Hz, for 600 \Omega$ 26  26 $to 10 ta 3400 Hz, for 600 \Omega$ 26  26 $to 10 ta 3400 Hz, for 600 \Omega$ 26  26 $to 10 ta 3400 Hz, for 600 \Omega$ 26  26 $to 10 ta 3400 Hz, for 600 \Omega$ 26  26 $to 10 ta 3400 Hz, for 600 \Omega$ 26  26 $to 1$	to 50 kHz  20  40    ik to 100k  15  30 $= 600 \Omega, 300 \text{ to } 3400 \text{ Hz}, 0$ Bm, Active and Reverse blarity  46  63 $Sm$ , Active and Reverse blarity  46  63 $Sm$ , Active and Reverse blarity  40  50    TIP) or B(RING)  30  1  5    ID or B(RING), to 100 Hz  18  26  35    Iow  18  26  35    Iow  18  26  35    Iow  18  9.54  9.74    9.34  9.54  9.74    IBm, 1 kHz  -9.74  -9.54  -9.34    IBm, 1 kHz  3.32  3.52  3.72    IBm, 1 kHz  -6.42  -6.02  -5.62    re Test:, Standby, < [20 mA]	ito 50 kHz  20  40    ik to 100k  15  30    = 600 Ω, 300 to 3400 Hz, 0  30  63  dB    sm, Active and Reverse blarity  46  63  mA    KHz, 0 dBm  40  50  mA    TIP) or B(RING)  30  mA  mA    TIP) or B(RING), to 100 Hz  1  5  Ω/pin    low  18  26  35  mA    00 to 3400 Hz, for 600 Ω  26

Specification	Condition	Min	Тур	Max	Unit	Note
Gain Accuracy over frequency	Relative to gain at 1 kHz 300 to 3400 Hz	-0.1		+0.1		
Gain tracking at 1 kHz,	-30 dBm to +3 dBm, 2-Wire	-0.1		+0.1		
relative to 0 dBm	-55 dBm to -30 dBm, 2-Wire	-0.1		+0.1		<u>4.</u>
Gain tracking, On Hook,	0 to30 dBm, 2-wire	-0.15		+0.15	dB	<u>4.,5.</u>
relative to 0 dBm	+3 to 0 dBm, 2-wire	-0.35		+0.35		4.,0.
THD (Total Harmonic Distortion)	0 dBm, 2-wire, 1 kHz		-64	-50		
	+7 dBm, 2-wire, 1 kHz		-55	-40		
THD, On hook	0 dBm, 2-wire, 1 kHz			-36		<u>5.</u>
Overload Level, 2-Wire	Active or Polarity Reversal	2.5			V	<u>2.</u>
ICN	C-message		12	15	dBrnC	<u>4.</u>
ICN	Psophmetric		-78	-75	dBmP	
CFILT <sub>i</sub>	Output impedance		8000		Ω	
Shell	Drive capability, Active State	-150		+150	μA	<u>3.</u> , <u>6.</u>
	Input impedance		5		Ω	
VHP <sub>i</sub>	Offset voltage with respect to V <sub>REF</sub>	-20		+20	mV	<u>3.,7.</u>
	Offset voltage with respect to V <sub>REF</sub>	-40		+40	mV	<u> </u>
	Capacitive load on VOUT to AGND			100	pF	<u>3.</u>
VOUT <sub>i</sub>	Resistive load on VOUT to AGND	20			kΩ	<u>.</u>
	Drive capability, $R_L$ = 20 k $\Omega$	$\frac{V_{REF}-1}{20 \text{ k}}$		$\frac{V_{REF}+1}{20 \text{ k}}$	μA	<u>3.,7.</u>
	VOUT Output Range	0.4		2.4	V	
	VOUT Common Mode		1.4		v	
	Offset voltage voice	-20		+20	mV	<u>3.</u>
VINP – VINM	Differential Input Impedance	200			kΩ	<u>.</u>
	Differential Mode Input	-1		1	V	
	VINP, VINM Input Range	-0.3		2.4	, i i i i i i i i i i i i i i i i i i i	
Motoring goin	R <sub>L</sub> = 300 Ω, 12.0 kHz, Active	0	0.25	0.5	dB	<u>4.</u>
Metering gain	R <sub>L</sub> = 300 Ω, 16.0 kHz, Active	0	0.25	0.5	uВ	
Metering distortion,	Frequency = 12 kHz, Active		45	40	-ID	<u>4.</u>
R <sub>L</sub> = 300 Ω, V <sub>AB</sub> = 1.5 Vpk	Frequency = 16 kHz, Active		-45	-40	dB	
Crosstalk Between Channels						
Crosstalk coupling loss	F = 200 Hz to 3.4 kHz			-75	dB	
Logic Interface		<u> </u>				
Inputs (C1, C2)						
V <sub>IL</sub>				0.8		
V <sub>IH</sub>		2.0			V	
I	V <sub>IN</sub> = 0.4 V	-100	0	100		
	V <sub>IN</sub> = 2.4 V	-100	30	100	μA	
CHS <sub>IL</sub>	$V_{IN} = 50 \text{ mV}$		90	100		1
			30		μA	<u>4.</u>
CHS <sub>Float_Leakage</sub>		–1		+1		<u>4.</u>

### Le9502

Specification	Condition	Min	Тур	Max	Unit	Note
Outputs ( $\overline{F}_1$ , $\overline{F}_2$ )						
V <sub>OH</sub>	I <sub>OUT</sub> = –25 μA	2.4	2.8		v	
V <sub>OL</sub>	I <sub>OUT</sub> = 25 μA		0.2	0.4	v	
DET Pin Characteristics		····				
V <sub>OH</sub>	I <sub>OUT</sub> = –165μA	2.4	2.8		v	
V <sub>OL</sub>	I <sub>OUT</sub> = 165 μA		0.2	0.4		

Note:

1.  $V_{AB}$  = Voltage between the  $A_i$  (TIP) and  $B_i$  (RING) pins.

2. Overload level is defined when THD = 1%.

3. Guaranteed by design.

4. Not tested in production. Parameter is guaranteed by characterization or correlation to other tests.

5. When On hook,  $R_{LDC}$  is open circuit,  $R_{LAC} = 600 \Omega$ .

6. Layout should have less than 10 pF from pin to ground.

7.  $V_{REF}$  is an internal value of typically  $V_{REF}$  = 1.4V.



Zarlink Semiconductor Inc. 9

\* Denotes pins that are common to both channels.

Note:

i = per channel component/pin

Data Sheet

Le9502

**TEST CIRCUIT** 



### APPLICATION CIRCUIT





Note:

\* Denotes pins that are common to both channels.

\*\*  $V_{CM}$  is the bias voltage, which is  $\ge$  (maximum ADC input voltage / 2)

\*\*\* Total fuse resistance =  $100\Omega$  guarantees a minimum DC load.

### LINE CARD PARTS LIST

The following list defines the parts and part values required to meet target specification limits for channel i of the line card (i = 1, 2). The protection circuit is included.

ltem	Quantity (see note 1)	Туре	Value	Tol. Rating Comments		Note		
C <sub>1</sub>	1	Capacitor	100 nF	10%	16 V	Panasonic / ECJ-1VB1C104K, 0603		
C <sub>BDi</sub>	2	Capacitor	27 nF	10%	16 V	Panasonic / ECJ-1VB1C273K, 0603		
C <sub>ESRi,</sub> C <sub>VREGi</sub>	4	Capacitor	0.1uF	10%	200 V	CalChip / GMB31X7R104K200NT, 1206		
C <sub>FOUTi</sub>	2	Capacitor	1 µF	10%	50 V	Panasonic / ECJ-1VC1H100D, 0603	 	
C <sub>HSi</sub>	2	Capacitor	1 nF	10%	50 V	Panasonic / ECJ-1VC1H102J, 0603		
C <sub>HPi</sub>	2	Capacitor	1.5 µF	10%	6.3 V	Panasonic / ECJ-2YB0J155K, 0805		
C <sub>LPFi</sub>	2	Capacitor	4.7 μF Tantalum	10%	6.3 V	Panasonic / ECS-T0JY475R, 1206		
C <sub>RAMP</sub>	1	Capacitor	470 pF	5%	50 V	Panasonic / ECJ-1VC1H471J, 0603		
C <sub>TRIPi</sub>	2	Capacitor	47 nF	10%	50 V	Panasonic / ECJ-1VB1C473K, 0603		
C <sub>SW</sub>	1	Capacitor	220 μF Alum. Elect.	20%	25 V	Panasonic / ECE-V1EA221UP, 8mmCan		
C <sub>SW1</sub>	1	Capacitor	100 nF	10%	50 V	Panasonic / ECJ-2YB1H104K, 0805		
C <sub>FLi,</sub>	2	Capacitor	2.2 µF	20%	200 V	United Chemi / THCR70E2D225MT, 3025		
C <sub>VREGii</sub>	2	Capacitor	1.0 µF	10%	300 V	Tecate / CMC-300/105KX1825T060		
D <sub>SWi</sub>	2	Diode	ES2C		2 A	General Semi. / ES2C, DO-214AA		
DD1	1	Diode	4148CC		200 mA	Fairchild / MMBD4148CC, SOT-23		
DD2i	2	Diode	BAV99		200 mA	Fairchild / BAV99, SOT-23		
L <sub>SWi</sub>	2	Inductor	47 µH		2.95 A	Cooper Coiltronics / DR127-470	70	
L <sub>VREGi</sub>	2	Inductor	150 µH		205 mA	Coilcraft 1812LS154X_B		
PTC <sub>1i</sub> , PTC <sub>2i</sub>	4	PTC	50 Ω			AsiaCom / MZ2L-50R		
Q <sub>RAMP</sub>	1	N-channel MOSFET	FDV301N			Fairchild / FDV301N, SOT-23		
Q <sub>SWi</sub>	2	PNP Transistor	FZT955		-140 V	Zetex / FZT955TA, SOT-223		
R <sub>BDi</sub>	2	Resistor	180 Ω	1%	1/8 W	Yageo / 9C08052A1800FKHFT, 0805		
R <sub>CLK</sub>	1	Resistor	1 k	1%	1/16 W	Panasonic / ERJ-3EKF1002V, 0603		
R <sub>DC</sub>	1	Resistor	34.8 k	1%	1/16 W	Panasonic / ERJ-3EKF3482V, 0603		
R <sub>IMTi</sub>	2	Resistor	84.5 k	1%	1/16 W	Panasonic / ERJ-3EKF84R5V, 0603		
R <sub>LIMi</sub>	2	Resistor	0.1 Ω	1%	1/4 W	Panasonic / ERJ-L14KF10CU, 1210		
R <sub>OUTi</sub>	2	Resistor	51 k	5%	1/16 W	Panasonic / ERJ-3GEYJ513V, 0603		
R <sub>SET</sub>	1	Resistor	68.1 k	1%	1/16 W	Panasonic / ERJ-3EKF6812V, 0603		
R <sub>TRIPi</sub>	2	Resistor	536 k	1%	1/16 W	Panasonic / ERJ-3EKF5363V, 0603		
U1	1	SLIC	Le9502	-	-	Zarlink / Le79502, 44-pin eTQFP		
U2	1	CODEC	-	-	-	-		
U3	1	Protection	TISP61089	-170V	30A	Bourns / TISP61089BDR, DOO8		

Note:

1. Quantities required for a complete two-channel solution.

### PHYSICAL DIMENSIONS

### 44-Pin eTQFP



SYMBOL	MILLIMETER					
STMBUL	MIN,	NOM,	MAX,			
A	—	—	1,20			
A1	0,05	—	0.15			
A2	0.95	1.00	1.05			
D	12.00 BSC,					
D1	10.00 BSC.					
E	12,00 BSC.					
Eí	10,00 BSC.					
R2	0.08	—	0.20			
Rt	0.08	—	—			
θ	0"	3,5*	7*			
θ1	0*	—	—			
θ₂	11*	12	13*			
θ₃	11"	12*	13*			
С	0.09	—	0.20			
L	0,45	0.60	0.75			
L <sub>1</sub>	1.00 REF					
S	0.20	_				
b	0,17	0,20	0,27			
е	0.80 BSC					
Da	8.00					
Е₂	8.00					
000	0.20					
bbb	0,20					
ccc	0,10					
ddd	0.20					
N	44					

### NOTES:

- 1. CONTROLLING DIMENSION IN MILLIMETER UNLESS OTHERWISE SPECIFIED.
- 2. DIMENSIONS "D1" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 mm PER SIDE. "D1" AND "E1" ARE MAXIMUM PLASTIC BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH.
- 3. DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE MAXIMUM "b" DIMENSION BY MORE TAHN 0.08 mm.
- 4. DAMBAR CAN NOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD IS 0.07 mm FOR 0.4 mm AND 0.5 mm PITCH PACKAGES.
- 5. SQUARE DOTTED LINE IS E-PAD OUTLINE.
- 6. "N" IS THE TOTAL NUMBER OF TERMINALS,

### Note:

Packages may have mold tooling markings on the surface. These markings have no impact on the form, fit or function of the device. Markings will vary with the mold tool used in manufacturing.

### **REVISION HISTORY**

### Revision A1 to B1

- In Absolute Maximum Ratings, the following changes were made:
  - Changed T<sub>A</sub> from 22.7° to 32°C/W
  - Added another note describing eTQFP package
- In Supply Currents and Power Dissipation, Ringing operation state, removed condition VIN = 0.7 VDC
- In *Device Specifications*, Metering gain, changed min, typ, and max values from 4.24, 4.44, and 4.64, respectively, to 0.2, 0, and 0.2, respectively
- In *Device Specifications*, Logic Interface, I<sub>IH</sub>, changed min and max values from ±40 to ±50.
- Updated Switching Power Supply block diagram
- Updated Application Circuit and Parts List
- Updated Physical Dimensions drawing

### **Revision B1 to C1**

- In *Features*, the following changes were made:
  - Removed (5V Tolerant) statement.
  - Changed "5REN" statement to "70 Vpk @ 5REN"
  - Changed "Up to 90 Vpk, Balanced" statement to "90 Vpk capable".
- In *Related Literature*, added references to Le9500 and Le9501 data sheets.
- In *Two-Wire Interface*, updated the paragraph under the "Ringing" section.
- In *Electrical Characteristics*, the following changes were made:
  - Removed "0° C <  $T_A$  < 70° C" statement.
  - Updated the entire table entry.
  - Changed "V\_IN" to "V\_RING" for Ringing State and in Note 3.
  - In *Device Specifications*, the following changes were made:
    - Increased VREG typical and maximum specifications.
    - Removed "R<sub>L</sub>=34.8 k $\Omega$  " from I<sub>LTH</sub> accuracy and added note 4.
    - Increased I<sub>SC</sub> typical and maximum specifications, and added R<sub>L</sub>=600  $\Omega$  case.
    - Updated DC feed graphic and  $I_{SC}$  nominal value to reflect typical value of ( $I_{LTH}$  + 17.0mA).
    - Added I<sub>L</sub> accuracy @  $R_L$ =600 $\Omega$  case.
    - Increased I<sub>offhook threshold</sub> typical and maximum specifications and merged "mA" column units.
    - Changed "Vin = 0.9 Vpk" references to "Vin = 0.7 Vpk".
    - Increased I<sub>RSC</sub> typical and maximum specifications and added note 4.
    - Added note 4. to "VRINGP, VRINGM Input Range".
    - Added note 7. to K<sub>R</sub> and Ringing distortion.
    - Adjusted SD<sub>i</sub>, V<sub>OH</sub> and V<sub>OL</sub> : minimum, typical and maximum values and merged "uA" column units.
    - Adjusted I<sub>LONG</sub> minimum and maximum specifications.
    - Added note 4. to "Negative foregin voltage threshold at  $V_A$  or  $V_B$ ".
    - Removed "TBD" references and filled with data accordingly.
    - Updated "Metering gain" minimum, typical, and maximum specifications.
    - Adjusted IIL, IIH, CHSIL, and CHSFloat Leakage minimum, typical, and maximum specifications.
    - Added note 4. to CHS<sub>IL</sub> and CHS<sub>Float\_Leakage</sub>.
    - Add Note. 7 definition.
- Updated Test Circuit, Application Circuit and Parts List.
- Added "\*\*\*" definition for PTCi fuse in Application Circuit.

### Revision C1 to D1

- Added green package OPN to <u>Ordering Information on page 1</u>
- Added Package Assembly on page 13
- In <u>Device Specifications</u>, Metering Gain, changed min/typ/max values from -0.5, .2, .05 to 0, .25, and .5, respectively.

- In *Electrical Characteristics*, the following changes were made:
- Updated the entire table entry.
- In Device Specifications, the following changes were made:
  - Increased V<sub>AB</sub> maximum specifications for Standby.
  - Lowered V<sub>REG</sub> minimum specifications.
  - Added " $I_{LTH}$  = 20mA" for  $I_{SC}$ , and  $I_L$ . This required increase in 'Condition' table size and squeezing the 'Note' column.
  - Increased I<sub>SC</sub> maximum specifications
  - Increased I<sub>trip threshold</sub> typical specifications and added "V<sub>REG</sub>i = -85V" in the 'Condition' column.
  - Removed note 7 definition and references to it from K<sub>R</sub> and Ringing distortion. Changed note 8 references to note 7 (as note 8 definition now defaults to note 7).
  - Increased I<sub>LONG</sub> typical specifications.
  - Added note 4. to "Gain tracking, On Hook, relative to 0 dBm".
  - Updated "Metering gain" minimum, typical, and maximum specifications.
  - Added "Active" for the 12kHz "Metering gain" and "Metering distortion".
- Updated Test Circuit, the following changes were made:
  - Changed CSW, CFL, CVREG, CHS, and LVREG values.

### **Revision E1 to F1**

- In *Electrical Characteristics*, the following changes were made:
  - Updated the 'Supply Currents and Power Dissipation' table entries for VREG and SLIC Power.
  - Updated the 'Device Specifications' table entries for V<sub>REG</sub>.
  - Added note 3. to ISET and RDC Input voltage tolerance.

### **Revision F1 to G1**

- In <u>Electrical Characteristics on page 14</u> the following changes were made:
- Updated SLIC Device Power typical specifications for Pol.Rev.: R<sub>L</sub>=300Ω.
- In <u>Device Specifications on page 15</u>, the following changes were made:
  - Increased V<sub>AB</sub> maximum specifications for Active or Reverse Polarity.

### Revision G1 to G2

- Made minor edits to *Features* on page 1.
- Added note to *Physical Dimensions* on page 22.

### **Revision G2 to G3**

• Added new headers/footers due to Zarlink purchase of Legerity on August 3, 2007.



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